TOSHIBA

Unit in mm

### TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

# T L G D 2 5 6

#### 2 CHIP LED LAMP FOR MESSAGE BOARD

2 Chip Series Connection

All Plastic Mold Type: Clear Transparent Lens

Low Drive Current, High Intensity Green Light Emission Recommended Forward Current: IF=15~20mA (DC)

- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- Wide Rediation: Suitable for Message Board (±45 deg)

## MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	$I_{\mathbf{F}}$	30	mA
Reverse Voltage	$v_{ m R}$	8	V
Power Dissipation	$P_{\mathbf{D}}$	170	mW
Operating Temperature Range	$T_{ m opr}$	-30~85	°C
Storage Temperature Range	$\mathrm{T_{stg}}$	-40~120	°C

1. ANODE 2. CATHODE **JEDEC** 

Weight: 0.35g

**EIAJ** 

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# ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

CHAF	RACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward V	oltage	$ m V_{f F}$	$I_{\mathbf{F}} = 20 \text{mA}$	_	4.3	5.4	V
Reverse Cu	ırrent	$I_{ m R}$	$V_R=8V$	_	_	5	$\mu$ A
Luminous	TLGD256	- I <sub>V</sub>	I <sub>F</sub> =20mA (Note)	85.0	150	<b>-</b>	
Intensity	TLGD256 (NP)			85.0	_	414	mcd
Peak Emis	sion Wave Length	$\lambda_{ m p}$	I <sub>F</sub> =20mA	_	567	_	nm
Spectral Li	ine Half Width	Δλ	$I_F = 20 \text{mA}$	_	25	_	nm

(Note) Rank selection carried out under next standard range respectively, although it needs  $\pm 15\%$  additionary for guaranteed limits.

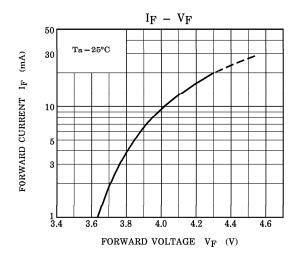
N: 100-200mcd P: 180-360mcd

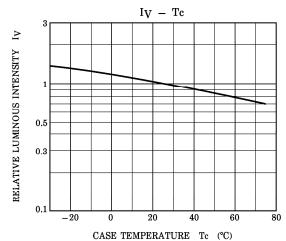
Each rank products is classified by package unit, and (NP) includes N and P.

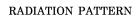
### **PRECAUTION**

Please be careful of the followings.

- Soldering temperature: 260°C MAX. Soldering time: 3s MAX. (Soldering portion of lead: below the Lead Stopper)
- If the lead is formed, the lead should be formed below the lead stopper without forming stress to the resin. Soldering should be performed after lead forming.







Ta = 25°C

